

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A method of depositing material on a substrate comprising the steps of arranging the material to be deposited in a container such that the material has a surface, and contacting said surface with a beam of electrons so as to evaporate the material and transfer the material to the substrate, a shield opaque to electrons being arranged to cover a portion of the surface ~~contacted by~~ including a location underneath the shield at which location said beam of electrons impacts the surface, and causing relative rotational movement between the container on one hand and the shield and the beam of electrons on the other hand such that said portion of the surface previously contacted by the beam of electrons is no longer covered by the shield and is exposed to the substrate.

Claim 2 (canceled).

Claim 3 (previously presented): A method according to claim 1, wherein the container is moved whilst the shield and beam of electrons are held stationary.

Claim 4 (canceled).

Claim 5 (currently amended): Apparatus for depositing material on a substrate, comprising a container for containing the material to be deposited, an electron gun for contacting the material with a beam of electrons so as to evaporate the material and transfer the material to the substrate, a shield opaque to electrons arranged to cover a portion of the container including a location underneath said shield at which location said beam of electrons impacts a surface of the material, and means for causing relative rotational movement between the container on one hand and the shield and electron gun on the other hand.

Claim 6 (previously presented): Apparatus according to claim 5, wherein the means for causing relative rotational movement comprises means for rotating the container about an axis.

Claim 7 (canceled).

Claim 8 (previously presented): Apparatus according to claim 6, further comprising means additional to the electron gun for heating the material.

Claim 9 (previously presented): Apparatus according to claim 5, further comprising means additional to the electron gun for heating the material.

Claim 10 (previously presented): A method according to claim 1, further comprising the step of heating the material by means of a heat source additional to the beam of electrons.

Claim 11 (canceled).

Claim 12 (previously presented): A method according to claim 3, further comprising the step of heating the material by means of a heat source additional to the beam of electrons.

Claim 13 (new): A method of depositing material on a substrate, comprising the steps of:
arranging the material to be deposited in a container such that the material has a
surface;
arranging a shield opaque to electrons to cover a portion of the surface relative to
the substrate;
contacting the surface with a beam of electrons such that the beam of electrons is
incident on the portion of the surface covered by the shield; and
causing relative rotational movement between the container on one hand and the
shield and the beam of electrons on the other hand such that the portion of
the surface previously contacted by the beam of electrons is no longer
covered by the shield and is exposed to the substrate so as to evaporate the
material and transfer the material to the substrate.

Claim 14 (new): A method according to claim 13, wherein secondary electrons emitted from the material where the beam of electrons is incident on the surface are trapped by the shield and are prevented from reaching the substrate.